

DZ2S150×0L

Silicon epitaxial planar type

For constant voltage / For surge absorption circuit
DZ2J150 in SSMini2 type package

■ Features

- Excellent rising characteristics of zener current I_Z
- Low zener operating resistance R_Z
- Halogen-free / RoHS compliant
(EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)

■ Marking Symbol: UJ or UU

■ Packaging

Embossed type (Thermo-compression sealing) : 3 000 pcs / reel (standard)

■ Absolute Maximum Ratings $T_a = 25\text{ }^\circ\text{C}$

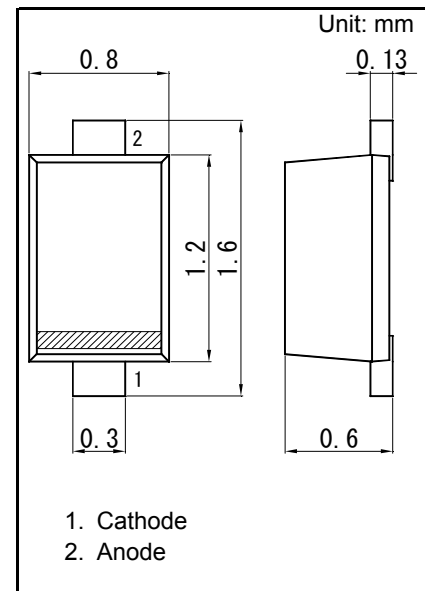
Parameter	Symbol	Rating	Unit
Repetitive peak forward current	IFRM	200	mA
Total power dissipation ^{*1}	PT	150	mW
Electrostatic discharge ^{*2}	ESD	±8	kV
Junction temperature	Tj	150	°C
Operating ambient temperature	Topr	-40 to +85	°C
Storage temperature	Tstg	-55 to +150	°C

Note) *1 Mounted on glass epoxy print board (45 mm × 45 mm × 1 mm)

Solder in (0.8 mm × 0.6 mm)

*2 Test method : IEC61000_4_2

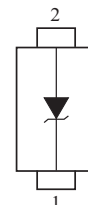
(C = 150 pF, R = 330 Ω, Contact discharge : 10 times)



1. Cathode
2. Anode

Panasonic	SSMini2-F5-B
JEITA	SC-79
Code	SOD-523

Internal Connection



■ Electrical Characteristics $T_a = 25\text{ }^\circ\text{C} \pm 3\text{ }^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	VF	IF = 10 mA			1.0	V
Zener voltage ^{*1, *2}	VZ	IZ = 5 mA	14.25		15.60	V
Zener operating resistance	RZ	IZ = 5 mA			40	Ω
Zener rise operating resistance	RZK	IZ = 0.5 mA			80	Ω
Reverse current	IR	VR = 11 V			0.05	μA
Temperature coefficient of zener voltage ^{*3}	SZ	IZ = 5 mA		13.4		mV/°C

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.

2. Absolute frequency of input and output is 5 MHz.

3. *1 The temperature must be controlled 25 °C for VZ measurement.

VZ value measured at other temperature must be adjusted to VZ (25 °C).

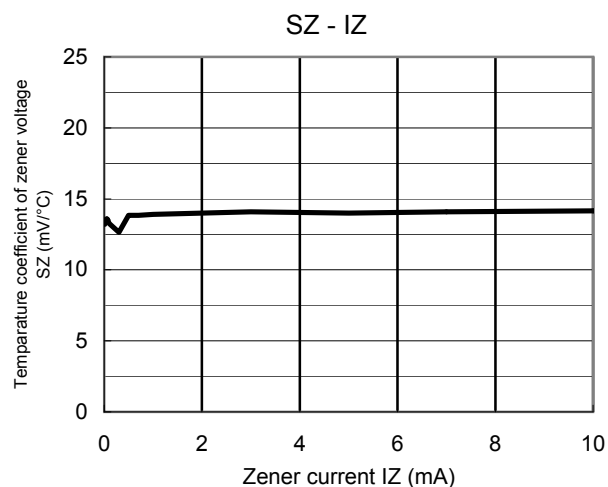
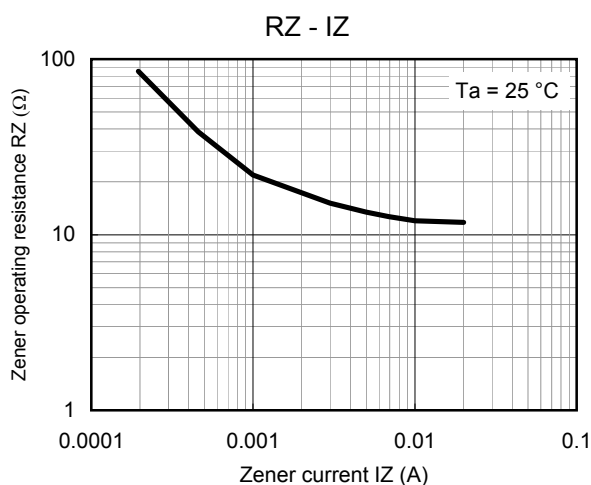
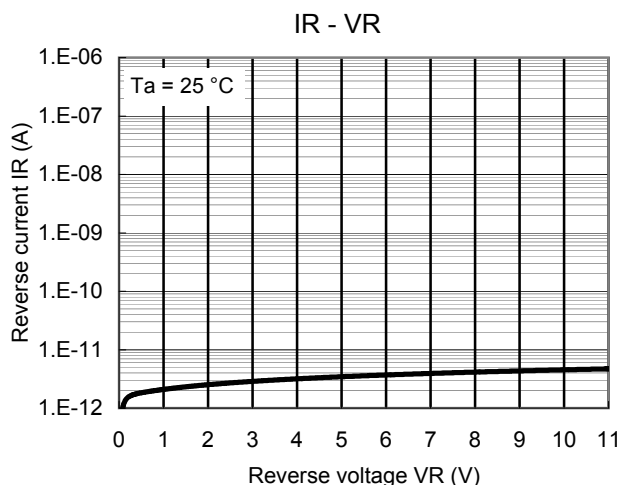
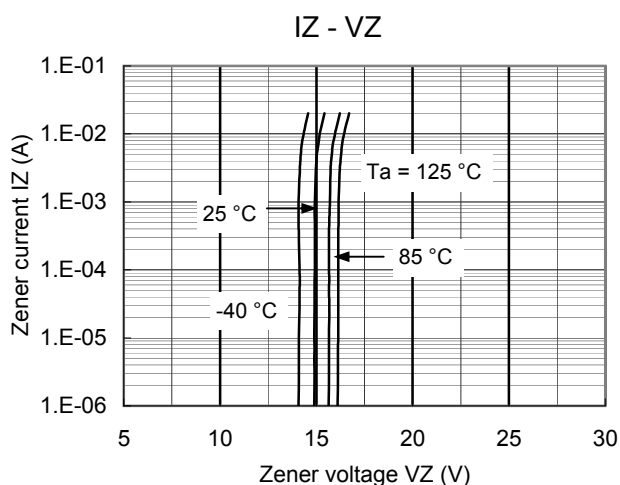
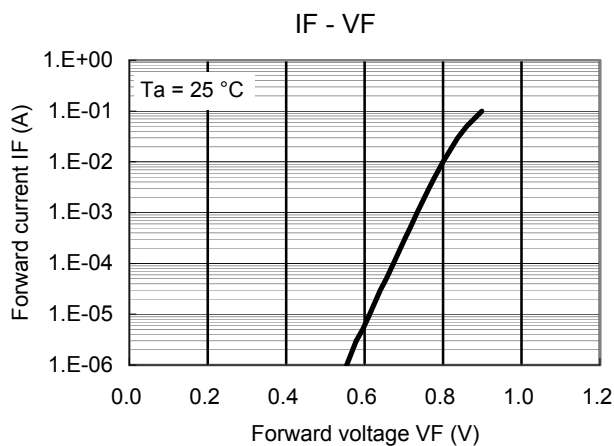
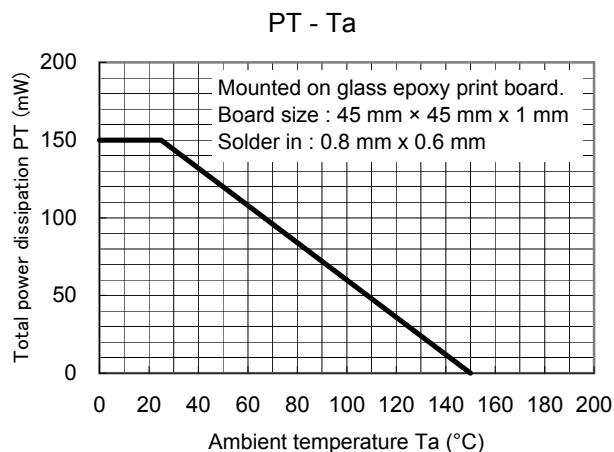
*2 VZ guaranteed 20 ms after current flow

*3 Tj = 25 °C to 150 °C

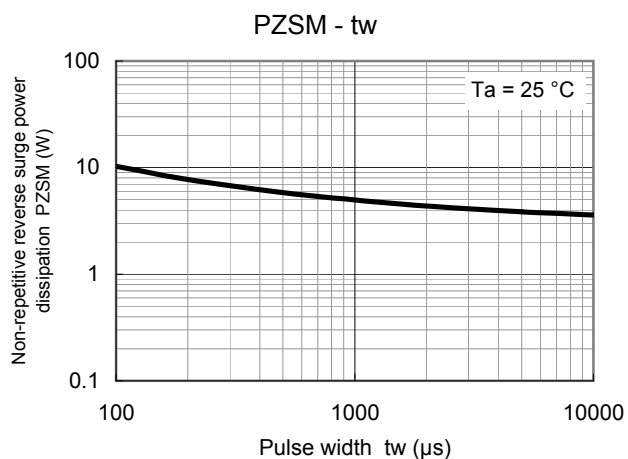
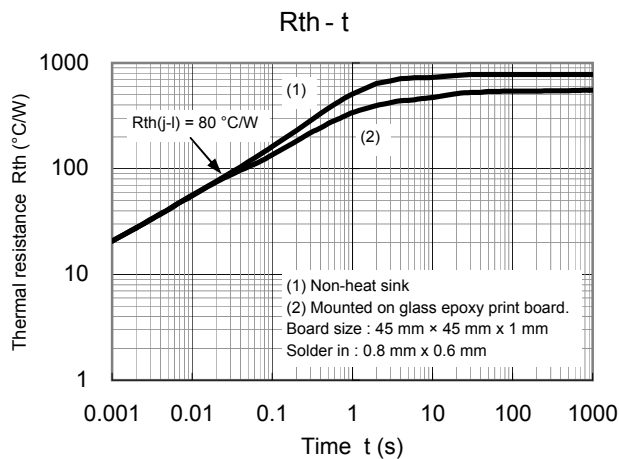
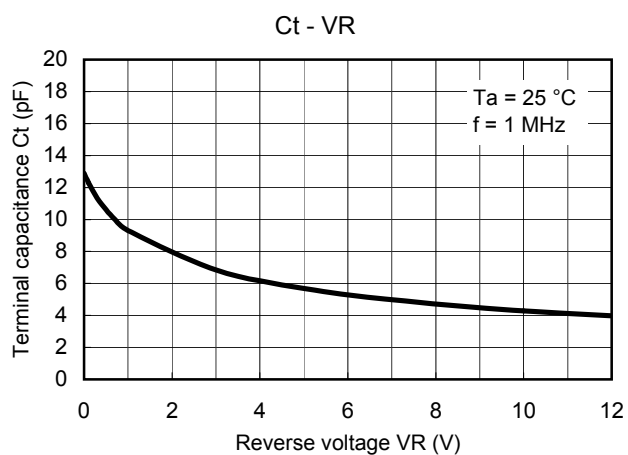
Rank classification

Code	M	0
Rank	M	No-rank
VZ	14.61 to 15.35	14.25 to 15.60
Marking symbol	UU	UJ

Technical Data (reference)

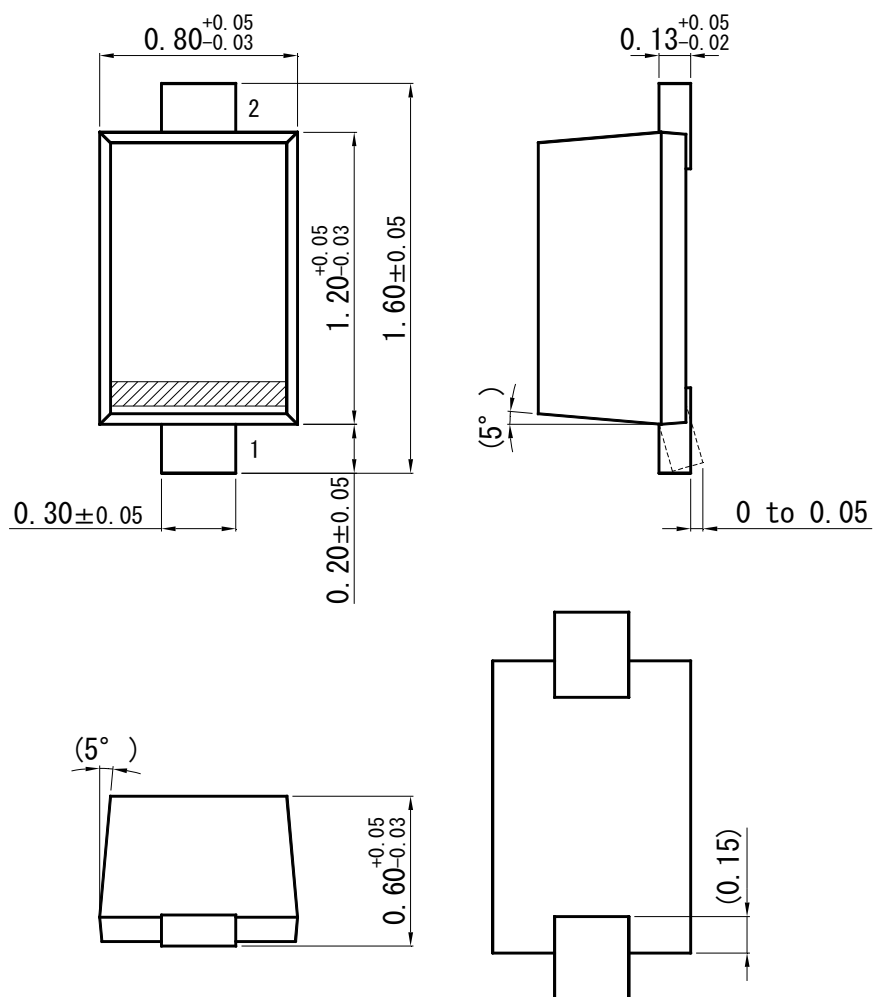


Technical Data (reference)

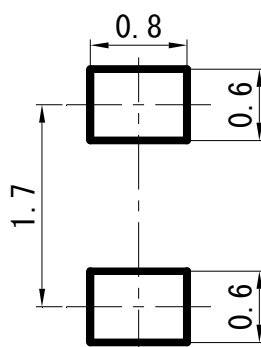


SSMini2-F5-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



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